

**COMPLEMENTARY PAIR ENHANCEMENT MODE MOSFET**
**Product Summary**

| Device | V <sub>(BR)DSS</sub> | R <sub>DS(on)</sub>             | I <sub>D</sub><br>T <sub>A</sub> = +25°C |
|--------|----------------------|---------------------------------|------------------------------------------|
| Q1     | 30V                  | 60mΩ @ V <sub>GS</sub> = 10V    | 3.4A                                     |
|        |                      | 100mΩ @ V <sub>GS</sub> = 4.5V  | 2.7A                                     |
| Q2     | -30V                 | 95mΩ @ V <sub>GS</sub> = -10V   | -2.8A                                    |
|        |                      | 140mΩ @ V <sub>GS</sub> = -4.5V | -2.3A                                    |

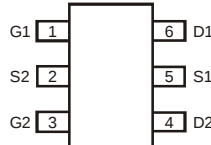
**Description and Applications**

This new generation MOSFET is designed to minimize the on-state resistance (R<sub>DS(on)</sub>) and yet maintain superior switching performance, making it ideal for high efficiency power management applications.

- Backlighting
- DC-DC Converters
- Power Management Functions



Top View



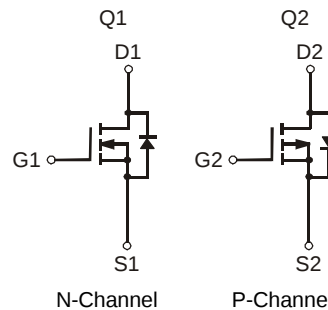
Top View

**Features and Benefits**

- Low On-Resistance
- Low Input Capacitance
- Fast Switching Speed
- Low Input/Output Leakage
- **Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. "Green" Device (Note 3)**
- **Qualified to AEC-Q101 Standards for High Reliability**
- **PPAP Capable (Note 4)**

**Mechanical Data**

- Case: TSOT26
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals Connections: See Diagram
- Terminals: Finish – Matte Tin Annealed over Copper Leadframe. Solderable per MIL-STD-202, Method 208
- Weight: 0.013 grams (Approximate)



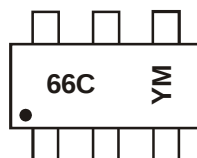
N-Channel

P-Channel

**Ordering Information** (Note 5)

| Part Number    | Case   | Packaging            |
|----------------|--------|----------------------|
| DMG6602SVTQ-7  | TSOT26 | 3,000 / Tape & Reel  |
| DMG6602SVTQ-13 | TSOT26 | 10,000 / Tape & Reel |

- Notes:
1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
  2. See [http://www.diodes.com/quality/lead\\_free.html](http://www.diodes.com/quality/lead_free.html) for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
  3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
  4. Automotive products are AEC-Q101 qualified and are PPAP capable. Automotive, AEC-Q101 and standard products are electrically and thermally the same, except where specified. For more information, please refer to [http://www.diodes.com/quality/product\\_compliance\\_definitions/](http://www.diodes.com/quality/product_compliance_definitions/).
  5. For packaging details, go to our website at <http://www.diodes.com/products/packages.html>.

**Marking Information**


66C = Product Type Marking Code  
 YM = Date Code Marking  
 Y = Year (ex: X = 2010)  
 M = Month (ex: 9 = September)

**Date Code Key**

| Year | 2010 | 2011 | 2012 | 2013 | 2014 | 2015 | 2016 | 2017 | 2018 | 2019 | 2020 |
|------|------|------|------|------|------|------|------|------|------|------|------|
| Code | X    | Y    | Z    | A    | B    | C    | D    | E    | F    | G    | H    |

| Month | Jan | Feb | Mar | Apr | May | Jun | Jul | Aug | Sep | Oct | Nov | Dec |
|-------|-----|-----|-----|-----|-----|-----|-----|-----|-----|-----|-----|-----|
| Code  | 1   | 2   | 3   | 4   | 5   | 6   | 7   | 8   | 9   | O   | N   | D   |

**Maximum Ratings – Q1** (@TA = +25°C unless otherwise specified.)

| Characteristic                                           |              |                        | Symbol           | Value | Unit |
|----------------------------------------------------------|--------------|------------------------|------------------|-------|------|
| Drain-Source Voltage                                     |              |                        | V <sub>DSS</sub> | 30    | V    |
| Gate-Source Voltage                                      |              |                        | V <sub>GSS</sub> | ±20   | V    |
| Continuous Drain Current (Note 7) V <sub>GS</sub> = 10V  | Steady State | T <sub>A</sub> = +25°C | I <sub>D</sub>   | 3.4   | A    |
|                                                          |              | T <sub>A</sub> = +70°C |                  | 2.7   |      |
| Continuous Drain Current (Note 7) V <sub>GS</sub> = 4.5V | Steady State | T <sub>A</sub> = +25°C | I <sub>D</sub>   | 2.7   | A    |
|                                                          |              | T <sub>A</sub> = +70°C |                  | 2.2   |      |
| Maximum Continuous Body Diode Forward Current (Note 5)   |              |                        | I <sub>S</sub>   | 1.5   | A    |
| Pulsed Drain Current (Note 5)                            |              |                        | I <sub>DM</sub>  | 25    | A    |

**Maximum Ratings – Q2** (@TA = +25°C unless otherwise specified.)

| Characteristic                                            |              |                                                  | Symbol           | Value        | Unit |
|-----------------------------------------------------------|--------------|--------------------------------------------------|------------------|--------------|------|
| Drain-Source Voltage                                      |              |                                                  | V <sub>DSS</sub> | -30          | V    |
| Gate-Source Voltage                                       |              |                                                  | V <sub>GSS</sub> | ±20          | V    |
| Continuous Drain Current (Note 7) V <sub>GS</sub> = -10V  | Steady State | T <sub>A</sub> = +25°C<br>T <sub>A</sub> = +70°C | I <sub>D</sub>   | -2.8<br>-2.4 | A    |
| Continuous Drain Current (Note 7) V <sub>GS</sub> = -4.5V | Steady State | T <sub>A</sub> = +25°C<br>T <sub>A</sub> = +70°C | I <sub>D</sub>   | -2.3<br>-2.1 | A    |
| Maximum Continuous Body Diode Forward Current (Note 7)    |              |                                                  | I <sub>S</sub>   | -1.5         | A    |
| Pulsed Drain Current (Note 7)                             |              |                                                  | I <sub>D</sub>   | -20          | A    |

**Thermal Characteristics**

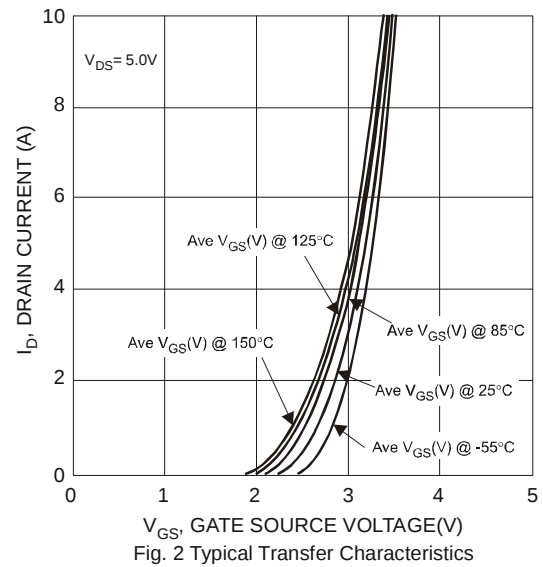
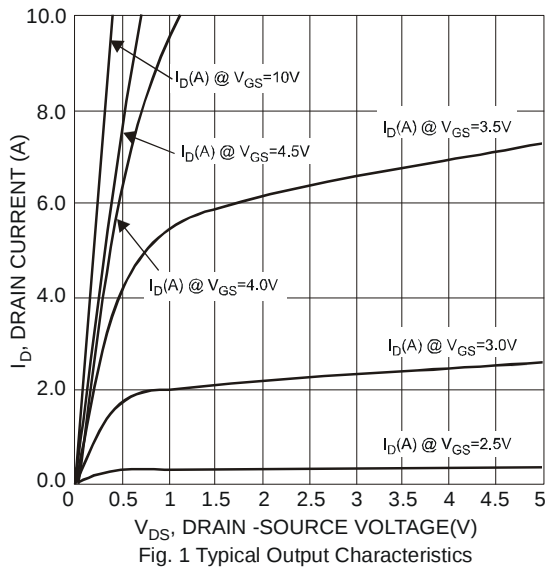
| Characteristic                                   |                        | Symbol                            | Value       | Units |
|--------------------------------------------------|------------------------|-----------------------------------|-------------|-------|
| Total Power Dissipation (Note 6)                 | T <sub>A</sub> = +25°C | P <sub>D</sub>                    | 0.84        | W     |
|                                                  | T <sub>A</sub> = +70°C |                                   | 0.52        |       |
| Thermal Resistance, Junction to Ambient (Note 6) | Steady State           | R <sub>θJA</sub>                  | 155         | °C/W  |
|                                                  | t < 10s                |                                   | 109         |       |
| Total Power Dissipation (Note 7)                 | T <sub>A</sub> = +25°C | P <sub>D</sub>                    | 1.27        | W     |
|                                                  | T <sub>A</sub> = +70°C |                                   | 0.8         |       |
| Thermal Resistance, Junction to Ambient (Note 7) | Steady State           | R <sub>θJA</sub>                  | 102         | °C/W  |
|                                                  | t < 10s                |                                   | 71          |       |
| Thermal Resistance, Junction to Case (Note 7)    |                        | R <sub>θJC</sub>                  | 34          |       |
| Operating and Storage Temperature Range          |                        | T <sub>J</sub> , T <sub>STG</sub> | -55 to +150 | °C    |

- Notes: 6. Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout.  
7. Device mounted on FR-4 substrate PC board, 2oz copper, with 1inch square copper plate.

**Electrical Characteristics – Q1 NMOS** (@  $T_A = +25^\circ\text{C}$  unless otherwise stated.)

| Characteristic                          | Symbol       | Min | Typ | Max       | Unit       | Test Condition                                               |
|-----------------------------------------|--------------|-----|-----|-----------|------------|--------------------------------------------------------------|
| <b>OFF CHARACTERISTICS (Note 8)</b>     |              |     |     |           |            |                                                              |
| Drain-Source Breakdown Voltage          | $BV_{DSS}$   | 30  | -   | -         | V          | $V_{GS} = 0V, I_D = 250\mu A$                                |
| Zero Gate Voltage Drain Current         | $I_{DSS}$    | -   | -   | 1.0       | $\mu A$    | $V_{DS} = 24V, V_{GS} = 0V$                                  |
| Gate-Source Leakage                     | $I_{GSS}$    | -   | -   | $\pm 100$ | nA         | $V_{GS} = \pm 20V, V_{DS} = 0V$                              |
| <b>ON CHARACTERISTICS (Note 8)</b>      |              |     |     |           |            |                                                              |
| Gate Threshold Voltage                  | $V_{GS(th)}$ | 1.0 | -   | 2.3       | V          | $V_{DS} = V_{GS}, I_D = 250\mu A$                            |
| Static Drain-Source On-Resistance       | $R_{DS(on)}$ | -   | 38  | 60        | m $\Omega$ | $V_{GS} = 10V, I_D = 3.1A$                                   |
|                                         |              |     | 55  | 100       |            | $V_{GS} = 4.5V, I_D = 2A$                                    |
| Forward Transfer Admittance             | $ Y_{fs} $   | -   | 4   | -         | S          | $V_{DS} = 5V, I_D = 3.1A$                                    |
| Diode Forward Voltage                   | $V_{SD}$     | -   | 0.8 | 1         | V          | $V_{GS} = 0V, I_S = 1A$                                      |
| <b>DYNAMIC CHARACTERISTICS (Note 9)</b> |              |     |     |           |            |                                                              |
| Input Capacitance                       | $C_{iss}$    | -   | 290 | 400       | pF         | $V_{DS} = 15V, V_{GS} = 0V, f = 1.2MHz$                      |
| Output Capacitance                      | $C_{oss}$    | -   | 40  | 80        |            |                                                              |
| Reverse Transfer Capacitance            | $C_{rss}$    | -   | 40  | 80        |            |                                                              |
| Gate Resistance                         | $R_g$        | -   | 1.4 | -         | $\Omega$   | $V_{DS} = 0V, V_{GS} = 0V, f = 1MHz$                         |
| Total Gate Charge ( $V_{GS} = 4.5V$ )   | $Q_g$        | -   | 4   | 6         | nC         | $V_{DS} = 15V, V_{GS} = 4.5V, I_D = 3.1A$                    |
| Total Gate Charge ( $V_{GS} = 10V$ )    | $Q_g$        | -   | 9   | 13        |            |                                                              |
| Gate-Source Charge                      | $Q_{gs}$     | -   | 1.2 | -         |            |                                                              |
| Gate-Drain Charge                       | $Q_{gd}$     | -   | 1.5 | -         |            |                                                              |
| Turn-On Delay Time                      | $t_{D(on)}$  | -   | 3   | -         | ns         | $V_{GS} = 10V, V_{DS} = 15V, R_G = 3\Omega, R_L = 4.7\Omega$ |
| Turn-On Rise Time                       | $t_r$        | -   | 5   | -         |            |                                                              |
| Turn-Off Delay Time                     | $t_{D(off)}$ | -   | 13  | -         |            |                                                              |
| Turn-Off Fall Time                      | $t_f$        | -   | 3   | -         |            |                                                              |

Notes: 8. Short duration pulse test used to minimize self-heating effect.  
9. Guaranteed by design. Not subject to product testing.



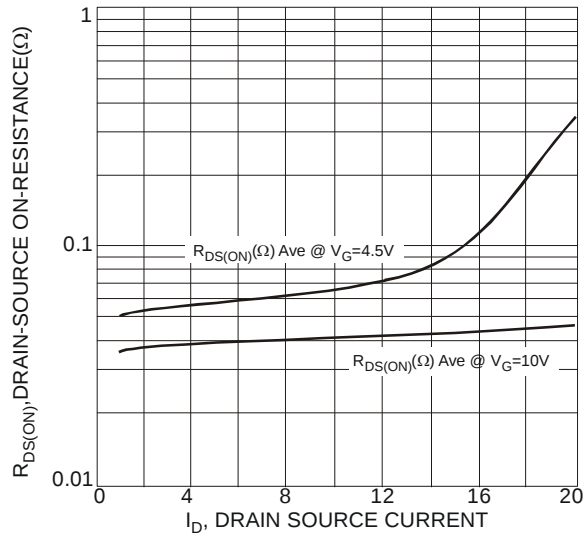


Fig. 3 Typical On-Resistance vs. Drain Current and Gate Voltage

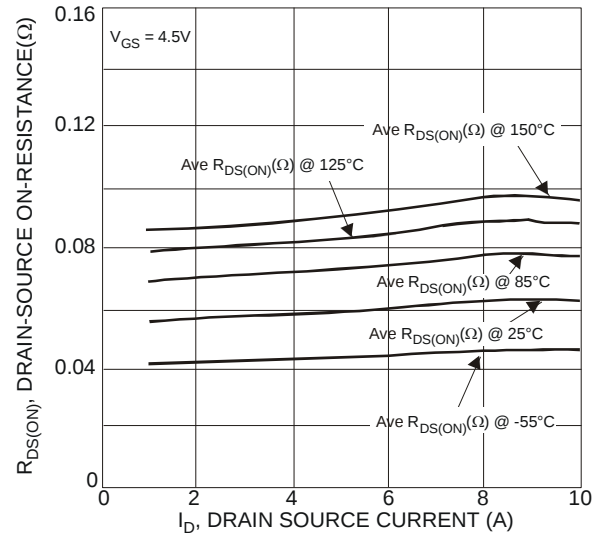


Fig. 4 Typical On-Resistance vs. Drain Current and Temperature

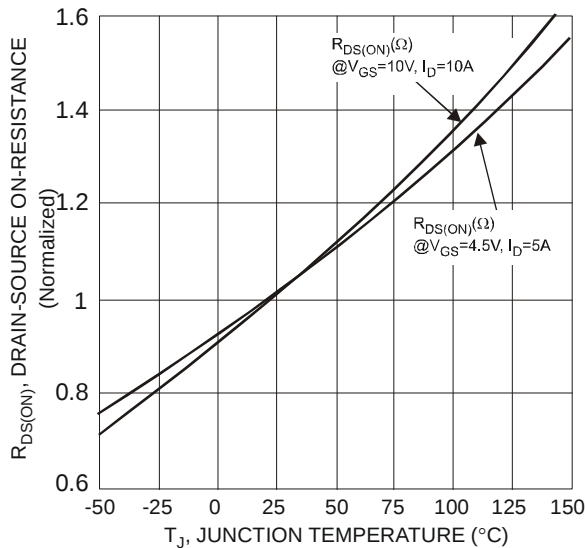


Fig. 5 On-Resistance Variation with Temperature

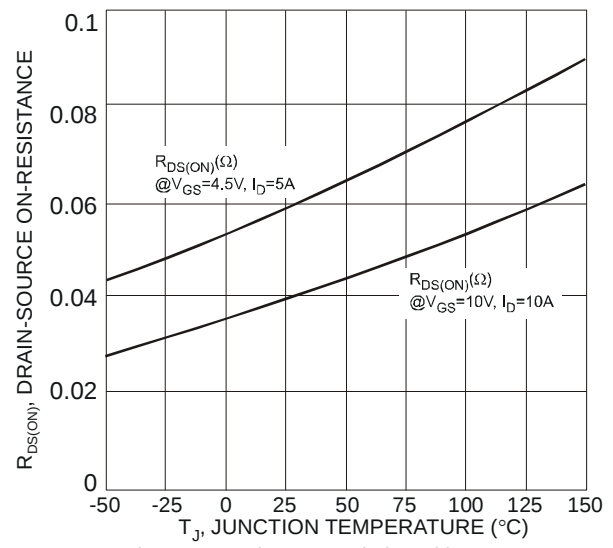


Fig. 6 On-Resistance Variation with Temperature

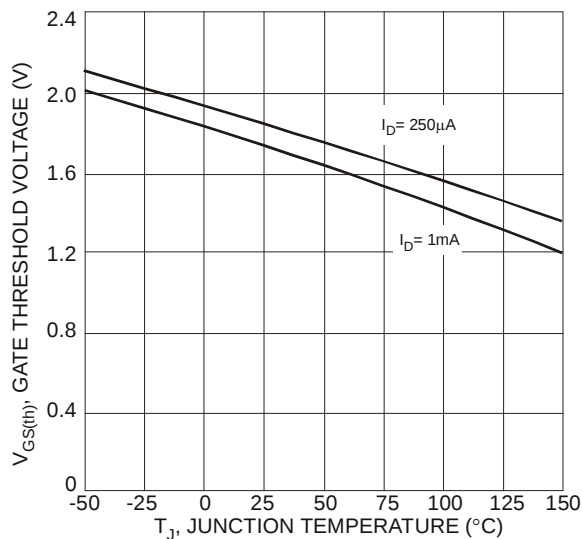


Fig. 7 Gate Threshold Variation vs. Ambient Temperature

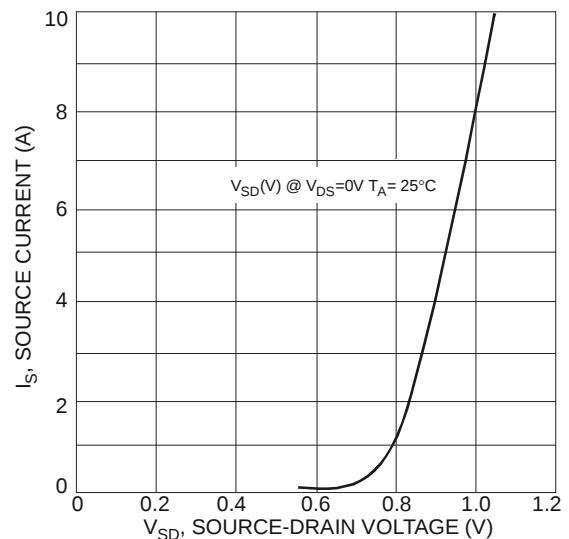
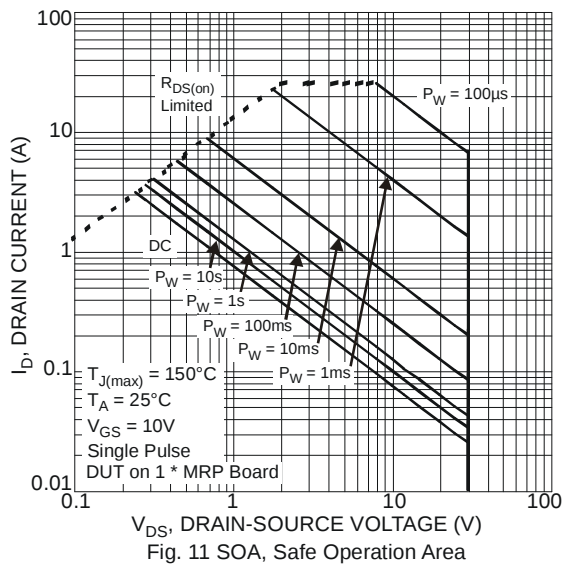
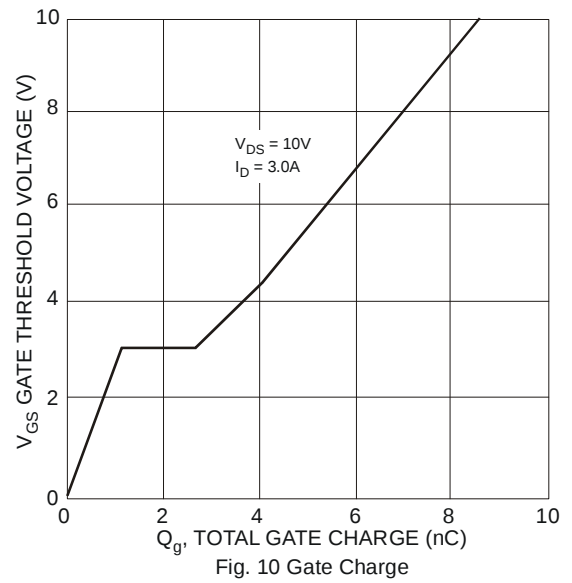
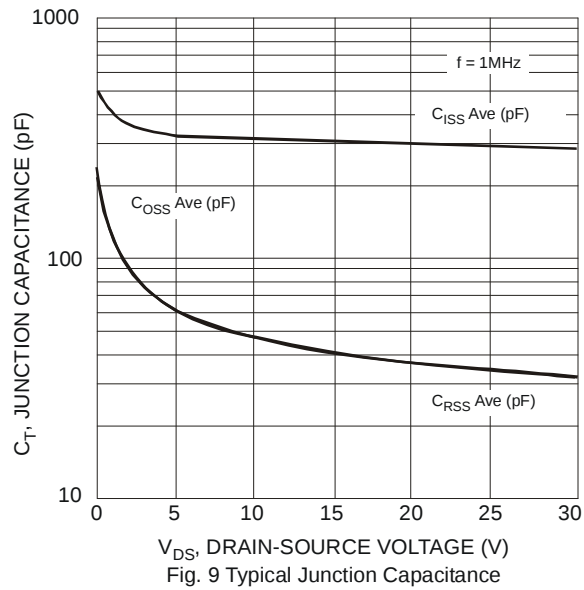


Fig. 8 Diode Forward Voltage vs. Current



# Electrical Characteristics – Q2 PMOS (@ T<sub>A</sub> = +25°C unless otherwise stated.)

| Characteristic                              | Symbol              | Min  | Typ      | Max       | Unit | Test Condition                                                                                  |
|---------------------------------------------|---------------------|------|----------|-----------|------|-------------------------------------------------------------------------------------------------|
| <b>OFF CHARACTERISTICS (Note 8)</b>         |                     |      |          |           |      |                                                                                                 |
| Drain-Source Breakdown Voltage              | BV <sub>DSS</sub>   | -30  | -        | -         | V    | V <sub>GS</sub> = 0V, I <sub>D</sub> = -250μA                                                   |
| Zero Gate Voltage Drain Current             | I <sub>DSS</sub>    | -    | -        | -1.0      | μA   | V <sub>DS</sub> = -24V, V <sub>GS</sub> = 0V                                                    |
| Gate-Source Leakage                         | I <sub>GSS</sub>    | -    | -        | ±100      | nA   | V <sub>GS</sub> = ±20V, V <sub>DS</sub> = 0V                                                    |
| <b>ON CHARACTERISTICS (Note 8)</b>          |                     |      |          |           |      |                                                                                                 |
| Gate Threshold Voltage                      | V <sub>GS(th)</sub> | -1.0 | -        | -2.3      | V    | V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = -250μA                                     |
| Static Drain-Source On-Resistance           | R <sub>DS(ON)</sub> | -    | 73<br>99 | 95<br>140 | mΩ   | V <sub>GS</sub> = -10V, I <sub>D</sub> = -2.7A<br>V <sub>GS</sub> = -4.5V, I <sub>D</sub> = -2A |
| Forward Transfer Admittance                 | Y <sub>fs</sub>     | -    | 6        | -         | S    | V <sub>DS</sub> = -5V, I <sub>D</sub> = -2.7A                                                   |
| Diode Forward Voltage                       | V <sub>SD</sub>     | -    | -0.8     | -1.0      | V    | V <sub>GS</sub> = 0V, I <sub>S</sub> = -1A                                                      |
| <b>DYNAMIC CHARACTERISTICS (Note 9)</b>     |                     |      |          |           |      |                                                                                                 |
| Input Capacitance                           | C <sub>iss</sub>    | -    | 350      | 420       | pF   | V <sub>DS</sub> = -15V, V <sub>GS</sub> = 0V,<br>f = 1.2MHz                                     |
| Output Capacitance                          | C <sub>oss</sub>    | -    | 50       | 100       |      |                                                                                                 |
| Reverse Transfer Capacitance                | C <sub>rss</sub>    | -    | 45       | 80        |      |                                                                                                 |
| Gate Resistance                             | R <sub>g</sub>      | -    | 17.1     | -         | Ω    | V <sub>DS</sub> = 0V, V <sub>GS</sub> = 0V, f = 1MHz                                            |
| Total Gate Charge (V <sub>GS</sub> = -4.5V) | Q <sub>g</sub>      | -    | 4        | 6         | nC   | V <sub>DS</sub> = -15V, V <sub>GS</sub> = -4.5V, I <sub>D</sub> = -3A                           |
| Total Gate Charge (V <sub>GS</sub> = -10V)  | Q <sub>g</sub>      | -    | 7        | 9         |      |                                                                                                 |
| Gate-Source Charge                          | Q <sub>gs</sub>     | -    | 0.9      | -         |      |                                                                                                 |
| Gate-Drain Charge                           | Q <sub>gd</sub>     | -    | 1.2      | -         | ns   | V <sub>GS</sub> = -10V, V <sub>DS</sub> = -15V,<br>R <sub>G</sub> = 6Ω, R <sub>L</sub> = 15Ω    |
| Turn-On Delay Time                          | t <sub>D(on)</sub>  | -    | 4.8      | -         |      |                                                                                                 |
| Turn-On Rise Time                           | t <sub>r</sub>      | -    | 7.3      | -         |      |                                                                                                 |
| Turn-Off Delay Time                         | t <sub>D(off)</sub> | -    | 20       | -         |      |                                                                                                 |
| Turn-Off Fall Time                          | t <sub>f</sub>      | -    | 13       | -         |      |                                                                                                 |

Notes: 8. Short duration pulse test used to minimize self-heating effect.  
9. Guaranteed by design. Not subject to production testing.

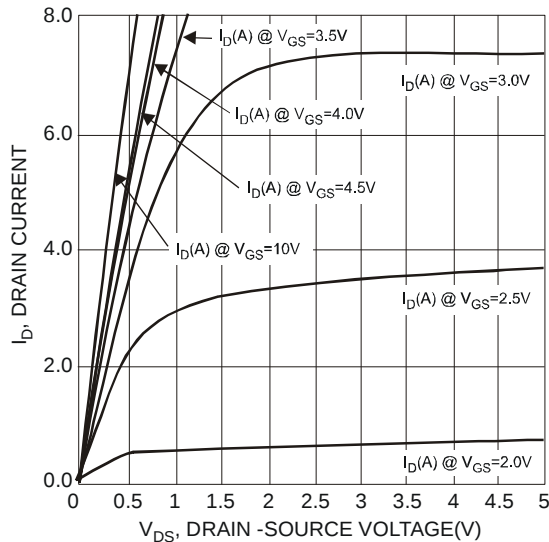


Fig. 12 Typical Output Characteristics

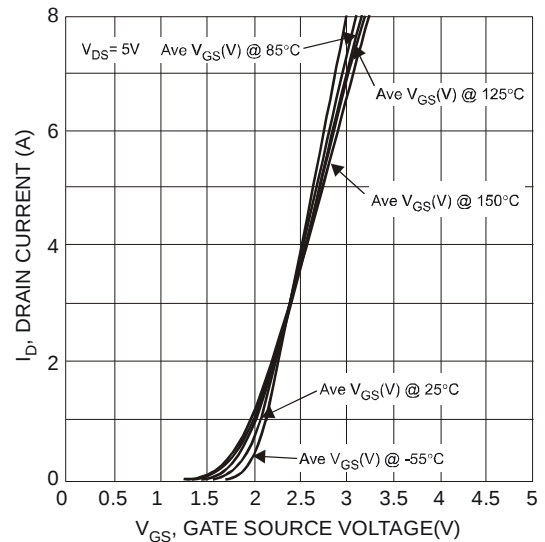


Fig. 13 Typical Transfer Characteristics

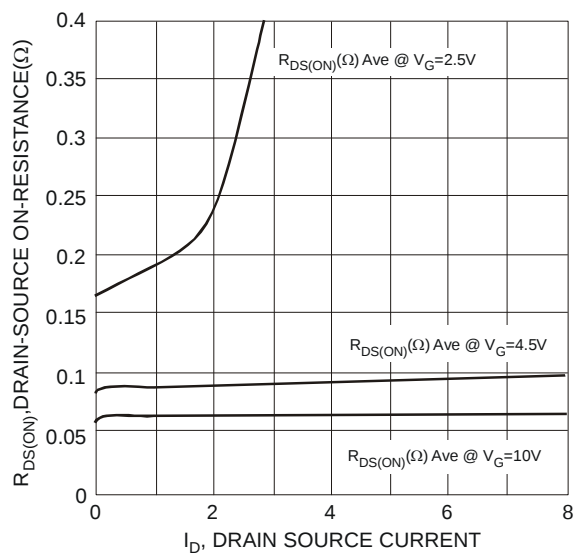


Fig. 14 Typical On-Resistance vs. Drain Current and Gate Voltage

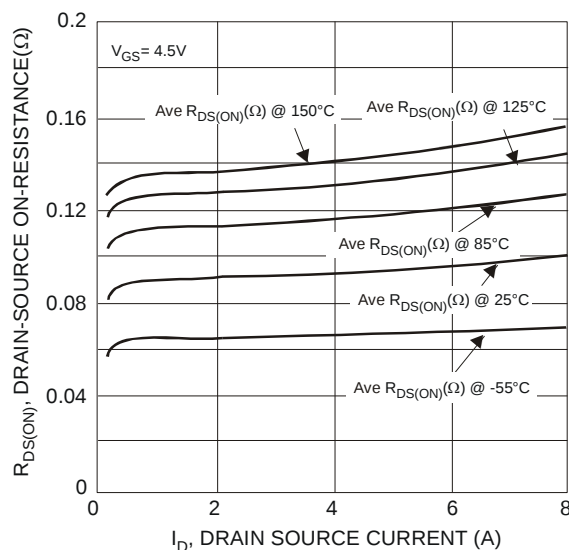


Fig. 15 Typical On-Resistance vs. Drain Current and Temperature

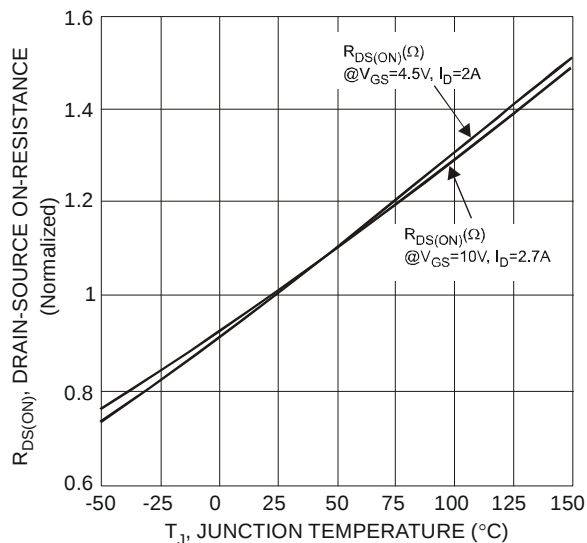


Fig. 16 On-Resistance Variation with Temperature

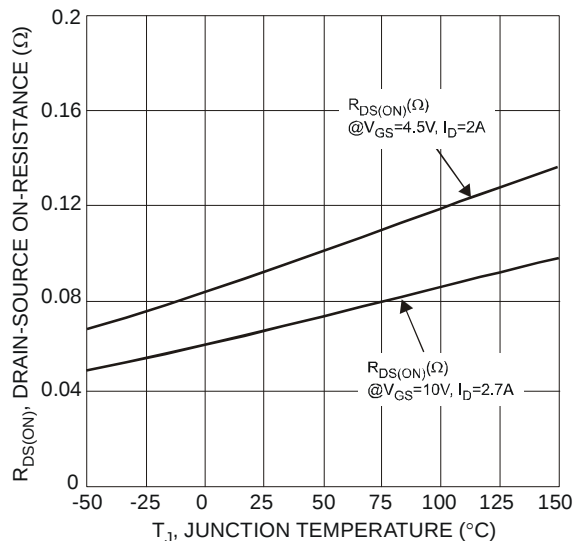


Fig. 17 On-Resistance Variation with Temperature

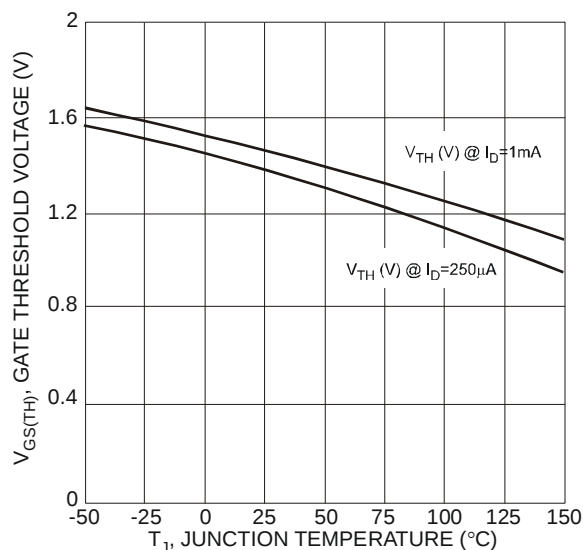


Fig. 18 Gate Threshold Variation vs. Ambient Temperature

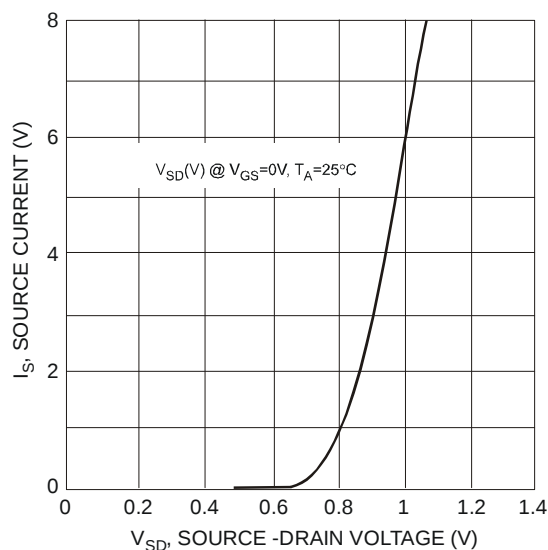
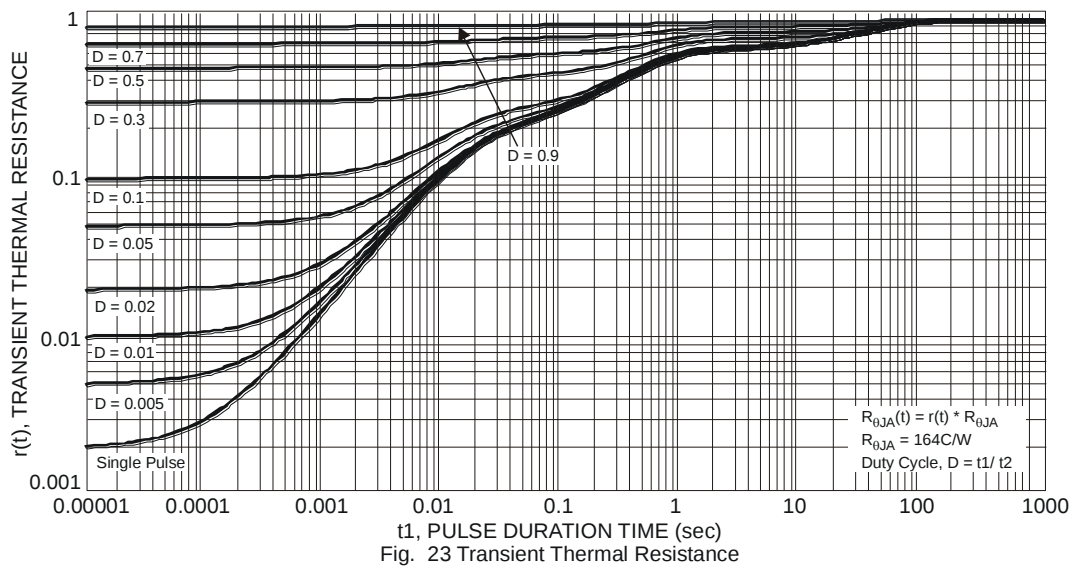
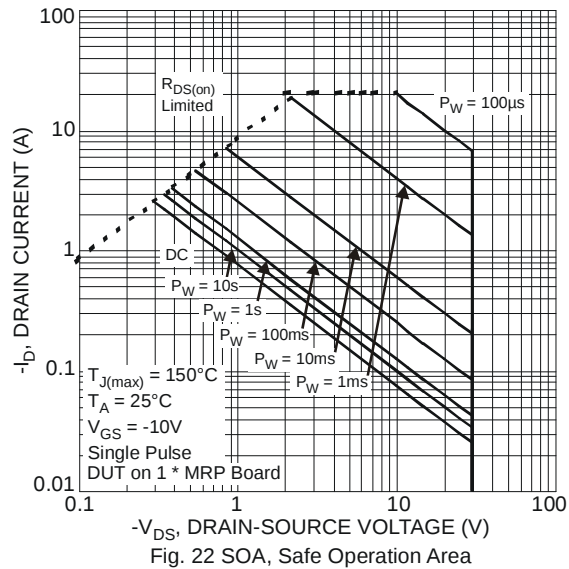
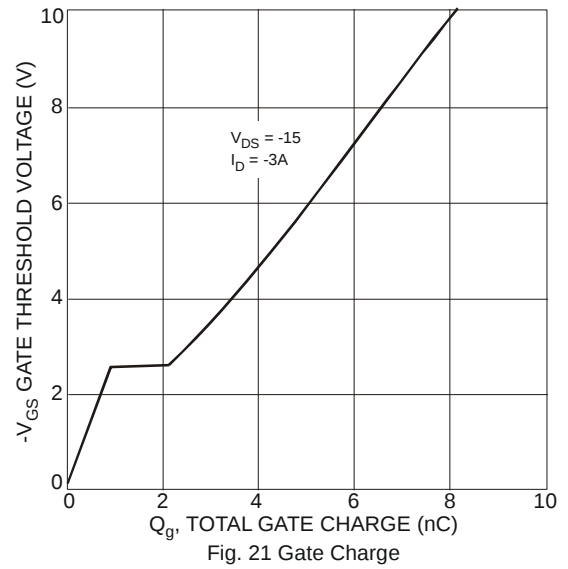
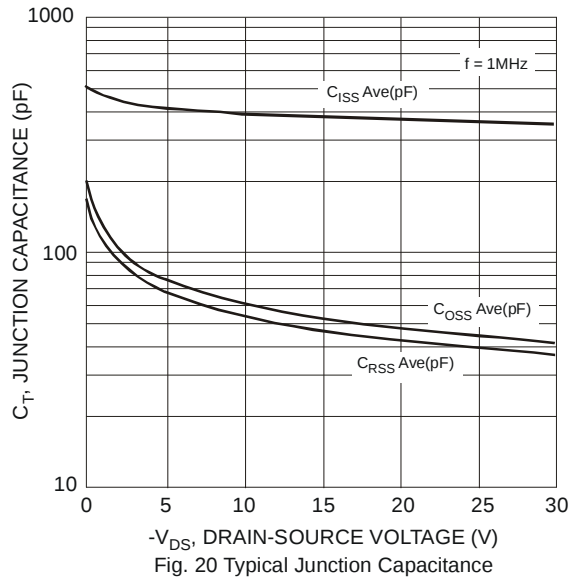
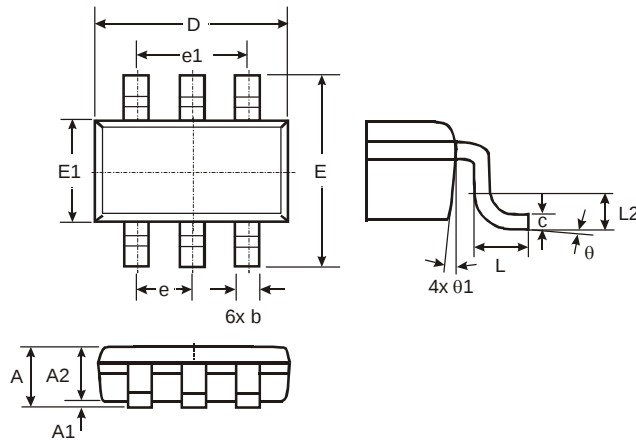


Fig. 19 Diode Forward Voltage vs. Current



## Package Outline Dimensions

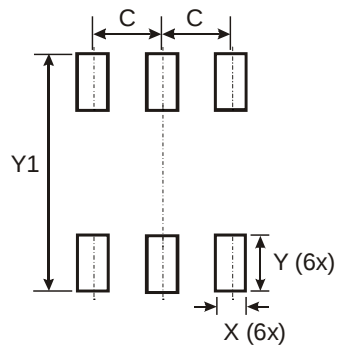
Please see AP02002 at <http://www.diodes.com/datasheets/ap02002.pdf> for the latest version.



| TSOT26               |      |      |      |
|----------------------|------|------|------|
| Dim                  | Min  | Max  | Typ  |
| A                    | —    | 1.00 | —    |
| A1                   | 0.01 | 0.10 | —    |
| A2                   | 0.84 | 0.90 | —    |
| D                    | —    | —    | 2.90 |
| E                    | —    | —    | 2.80 |
| E1                   | —    | —    | 1.60 |
| b                    | 0.30 | 0.45 | —    |
| c                    | 0.12 | 0.20 | —    |
| e                    | —    | —    | 0.95 |
| e1                   | —    | —    | 1.90 |
| L                    | 0.30 | 0.50 | —    |
| L2                   | —    | —    | 0.25 |
| θ                    | 0°   | 8°   | 4°   |
| θ1                   | 4°   | 12°  | —    |
| All Dimensions in mm |      |      |      |

## Suggested Pad Layout

Please see AP02001 at <http://www.diodes.com/datasheets/ap02001.pdf> for the latest version.



| Dimensions | Value (in mm) |
|------------|---------------|
| C          | 0.950         |
| X          | 0.700         |
| Y          | 1.000         |
| Y1         | 3.199         |

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